

APPROVAL SHEET

OverAir™ SMD Antenna series
RoHS Compliance

PN: OA-C07

2.4GHz bands antenna

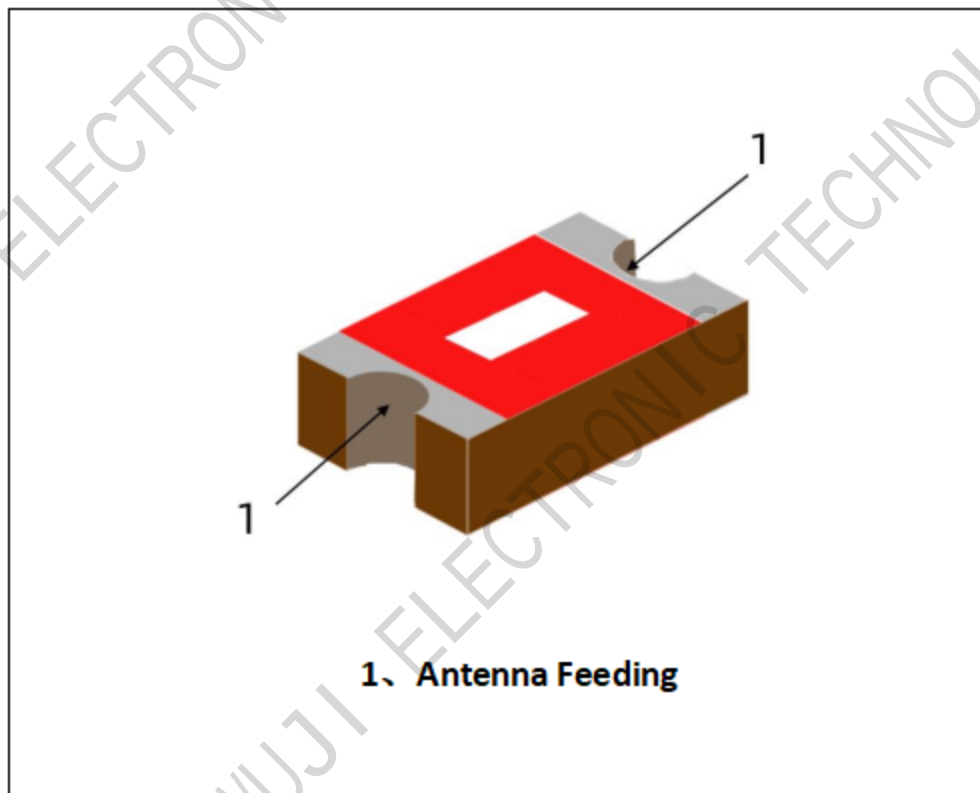
FEATURES

1. Surface Mounted Devices (SMD) with a small dimension of $3.5 \times 1.7 \times 1.2 \text{ mm}^3$ meet miniaturization trend.
2. Low power loss and high antenna efficiency.
3. High stability in Temperature and Humidity Change.

APPLICATIONS

1. 2.4GHz ISM band RF applications
2. WIFI (2.4GHz only)
3. Bluetooth,ZigBee, Wireless, HomeRF

CONSTRUCTION



DIMENSIONS

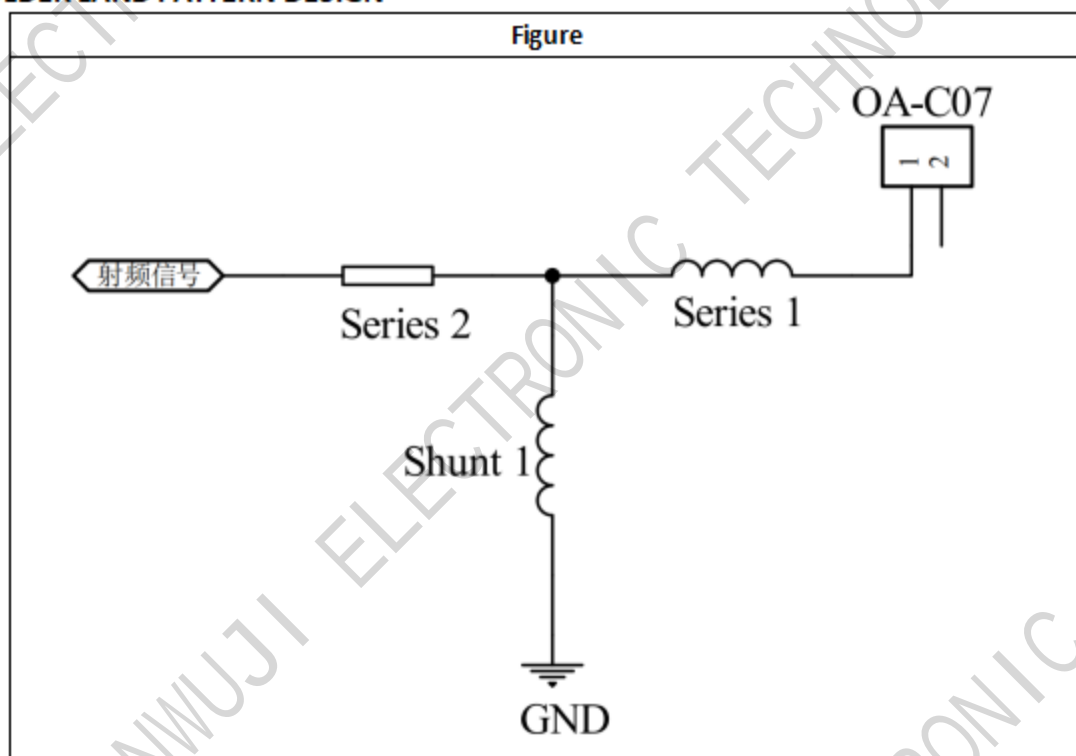
Figure	Symbol	Dimension(mm)
The figure shows two 2D views of the antenna component. The top view is a red square with a white square in the center. The dimensions are labeled: $a=0.4\text{mm}$ (width of the white square), $W=1.7\text{mm}$ (width of the red square), $L=3.5\text{mm}$ (length of the red square), and $T=1.2\text{mm}$ (thickness of the substrate). The side view shows the brown substrate with the red square on top.	L	3.5 ± 0.2
	w	1.7 ± 0.1
	T	1.2 ± 0.1
	a	0.4 ± 0.1

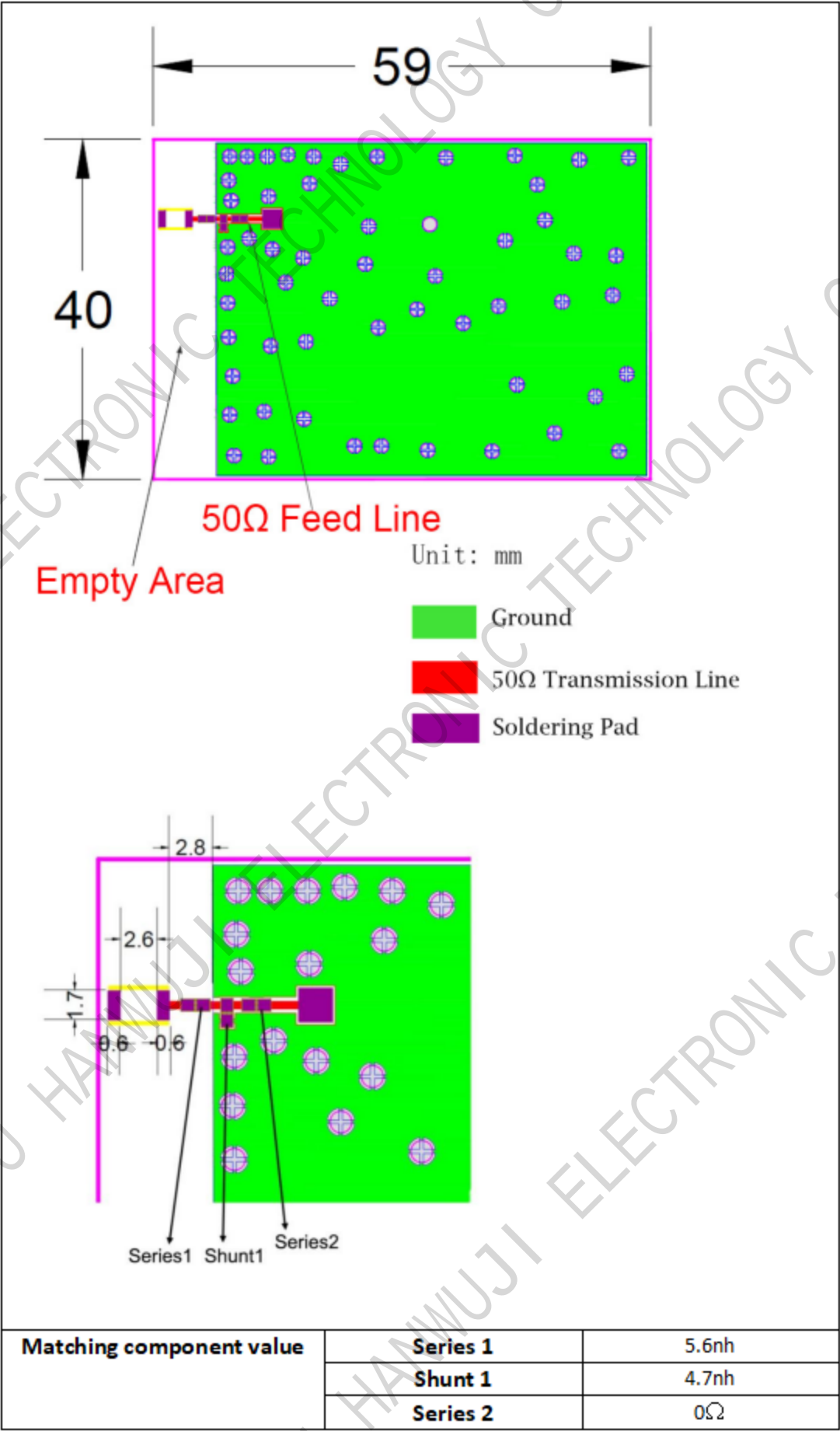
ELECTRICAL CHARACTERISTICS

OA-C07	Specification
Working Frequency Range	2450 ± 50MHz
Band Width	>100MHz
Impedance	50Ω
Gain(dBi)	3.74(peak)
VSWR	<2
Operation Temperature	-40℃~+95℃
Power Capacity	3W

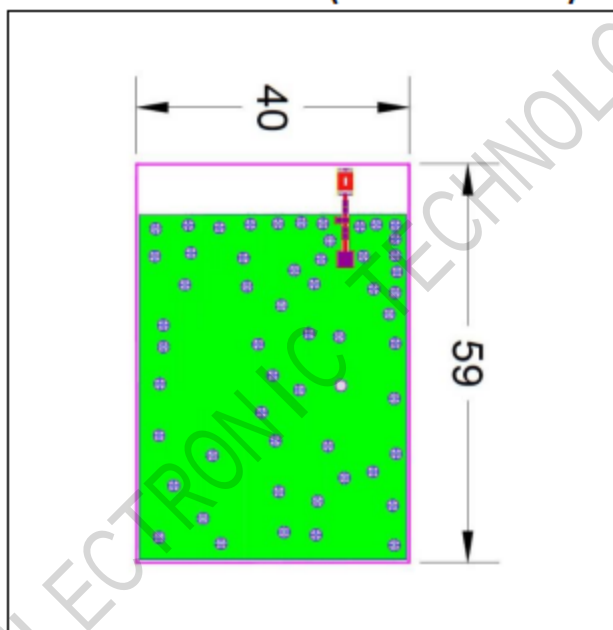
The working frequency need be adjusted to 2.45GHz with matching circuit.

SOLDER LAND PATTERN DESIGN

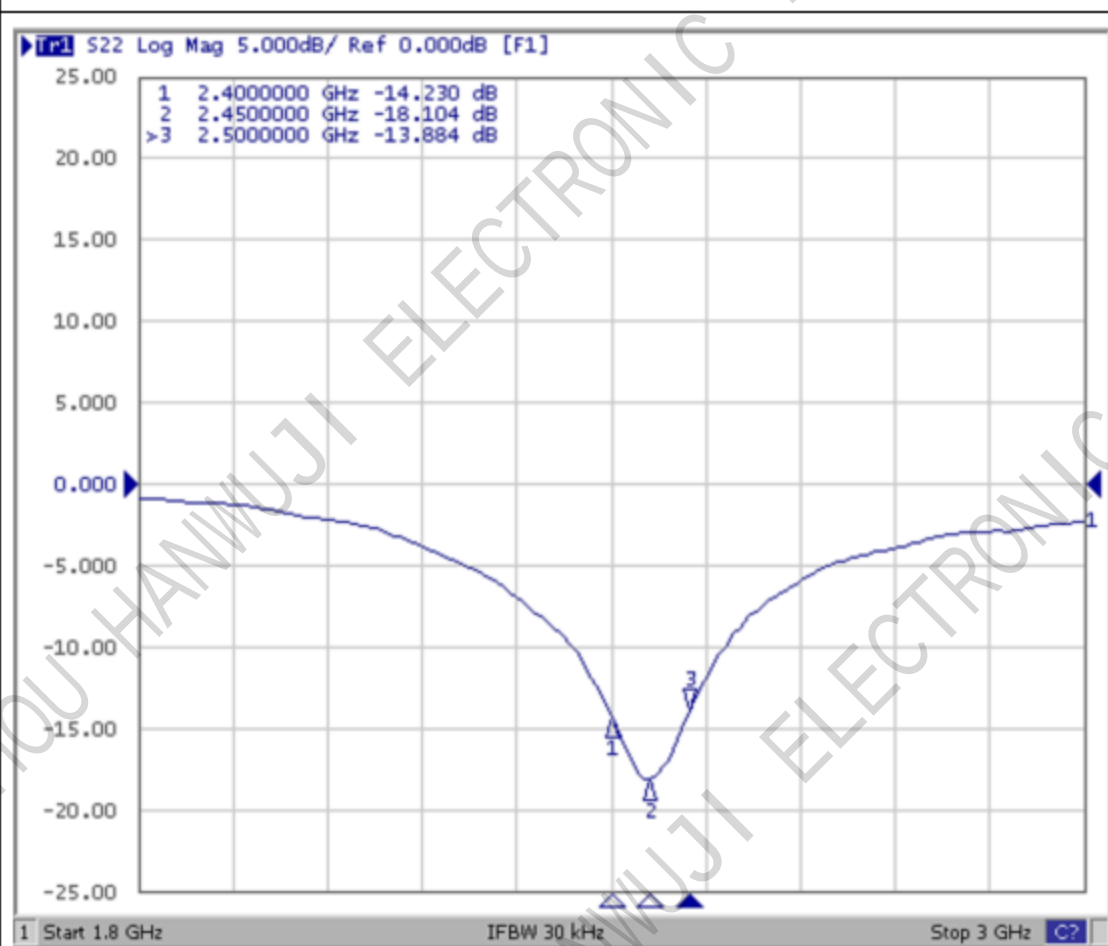


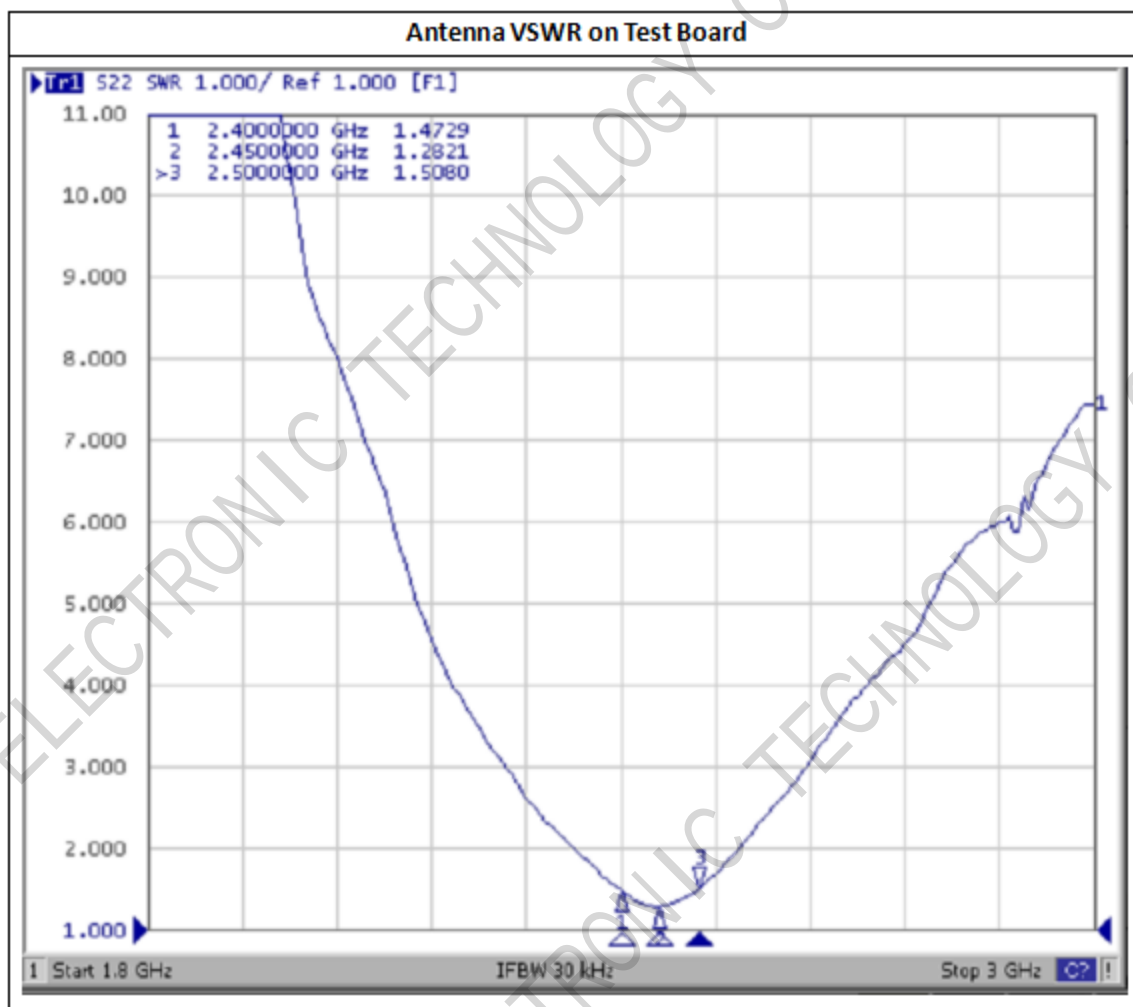


Antenna on Test Board (Thickness 1.0mm)



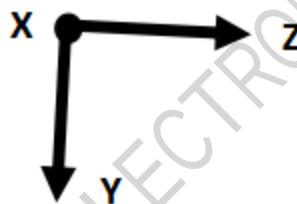
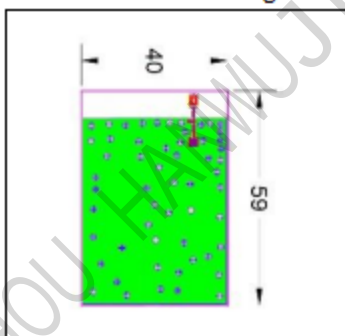
Antenna S11 on Test Board



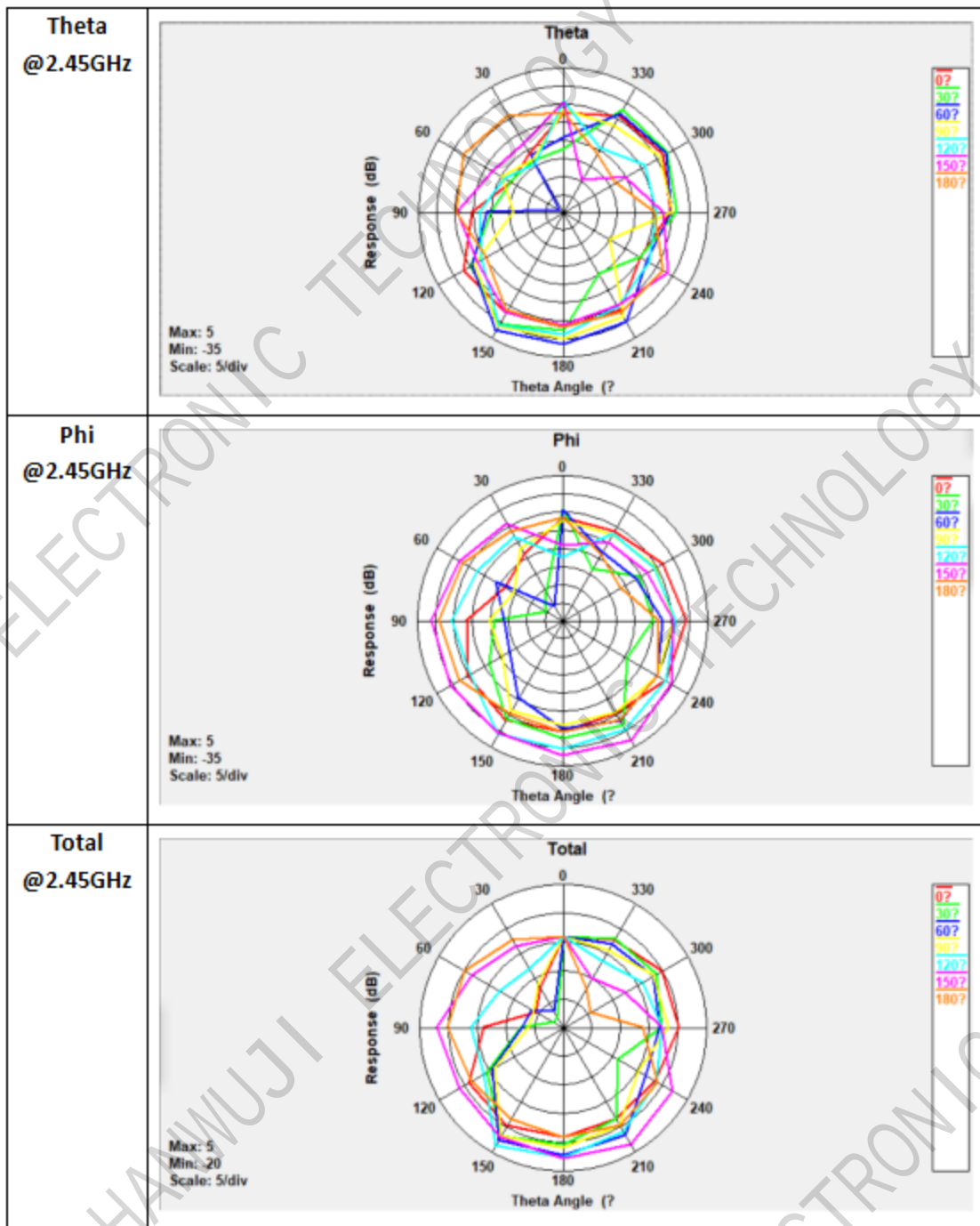


Efficiency and RADIATION PATTERN

Efficiency, Radiation Pattern and Gain were dependent on measurement board design. The specification of OA-C07 antenna was measured based on the PCB size and installation position as shown in the below figure test board. The test results were tested in ETS 3D Chamber.

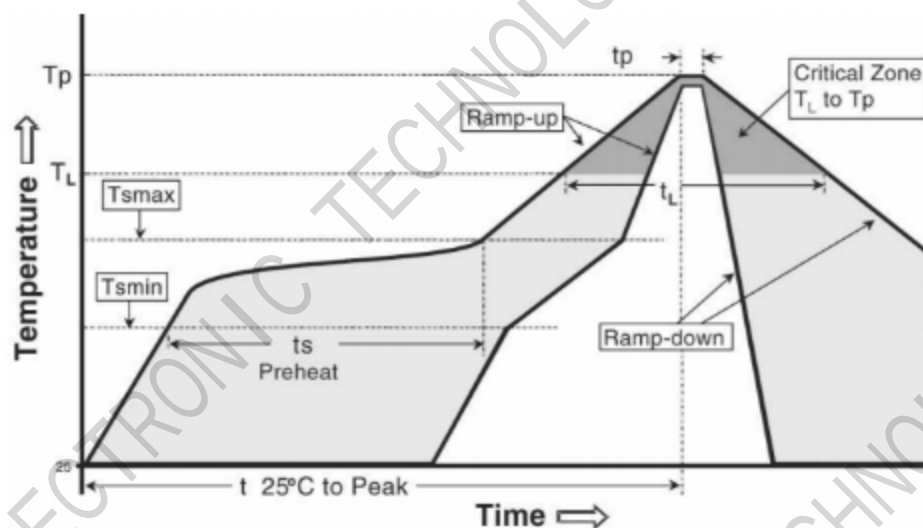


Gain and Efficiency	2.4G-2.5GHz
Peak Gain	3.74dBi
Average Gain across the band	3.66dBi
Gain Range across the band	3.42dBi~3.74dBi
Peak Efficiency	58.9%
Average Efficiency across the band	55.9%
Efficiency Range across the band	53.0%~58.9%



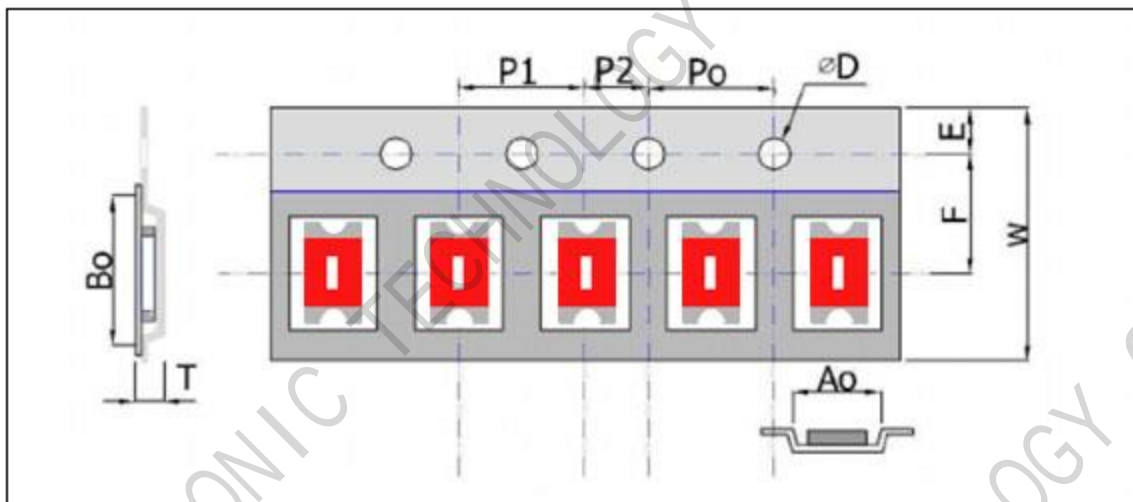
SOLDERING CONDITION

Typical examples of soldering processes that provide reliable joints without any damage is as follows:



Phase	Profile features	Pb-Free assembly (SnAgCu)
RAMP-UP	Avg. Ramp-up Rate (Tsmax to Tp)	3 °C / second (max.)
PREHEAT	- Temperature Min (Tsmmin) - Temperature Max (Tsmmax) - Time (tsmin to tsmax)	150 °C 200 °C 60-180 seconds
REFLOW	- Temperature (TL) - Total Time above TL (tL)	217 °C 60-150 seconds
PEAK	- Temperature (Tp) - Time (tp)	260 °C 20-40 seconds
RAMP-DOWN	Rate	6 °C/second max
Time from 25 °C to Peak Temperature		8 minutes max

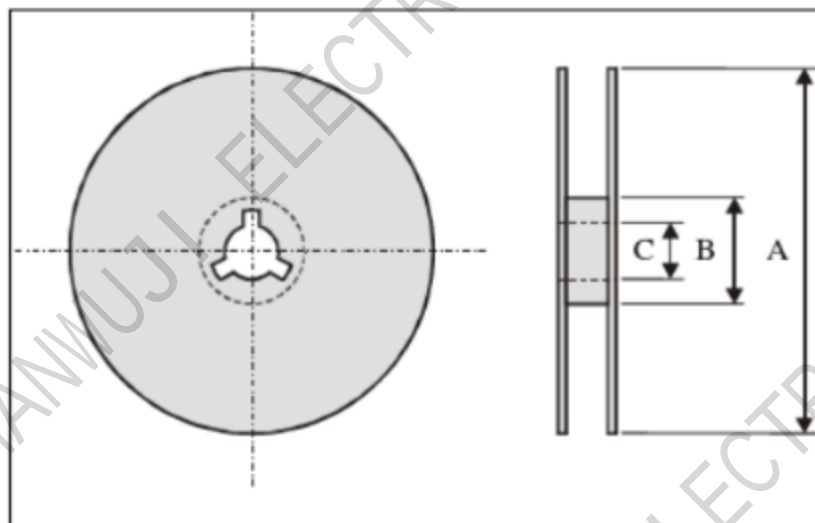
PACKAGING



Plastic Tape specification (unit:mm)

Index	Ao	Bo	ΦD	T	W
Dimension (mm)	2.0 ± 0.1	4.0 ± 0.1	1.55 ± 0.05	1.8 ± 0.1	12 ± 0.1
Index	E	F	Po	P1	P2
Dimension (mm)	1.5 ± 0.1	5.4 ± 0.1	4.0 ± 0.1	4.0 ± 0.1	2.0 ± 0.1

Reel dimensions



Index	A	B	C
Dimension(mm)	330	100	13.5

Typing Quantity: 2500 pieces per reel.

CAUTION OF HANDLING

Storage environment condition

Products should be storage in the warehouse on the following conditions:

Temperature : -10℃~+40℃

Humidity : 30% to 70% relative humidity

Don't keep products in corrosive gases such as sulfur. Chlorine gas or acid or it may cause oxidization of electrode, resulting in poor solderability.

Products should be storage on the palette for the prevention of the influence from humidity, dust and so on.

Products should be storage in the warehouse without heat shock, vibration, direct sunlight and so on.

Products should be storage under the airtight packaged condition.

Contact Us:

GUANGZHOU HANWUJI ELECTRONIC TECHNOLOGY CO., LTD

Add:1120, 11th Floor, Building 1, Hongda Creative Park, Yuanxiang Road, Yunpu Street, Huangpu District, Guangzhou

Name:Chen,Pengfei

Phone: 18028016875

Email: chenpengfei@hwjelec.com